As an inventor named below or on any attached continuation page, I hereby declare that:

My residence, post office address and citizenship are as stated next to my name.

I believe that I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled QUAD FLAT NO LEAD (QFN) GRID ARRAY PACKAGE, METHOD OF MAKING MEMORY MODULE AND COMPUTER SYSTEM INCLUDING SAME, the specification of which (check one):

□ is attached hereto. was filed on August 20, 2001 as United was filed on as PCT intern		amended under PCT Article 1	0	
	erstand the contents of the above-identified s			any amendment
10.01100 to 40000.				
I acknowledge the duty to disclose to the U matter claimed in this application, as "material	.S. Patent and Trademark Office all informatity" is defined in Title 37, Code of Federal R	ion known to me to be materia egulations § 1.56.	ıl to the patentabilit	y of the subject
I hereby claim foreign priority benefits und certificate or § 365(a) of any PCT international attached continuation page and have also ident any PCT international application(s) designation which priority is claimed.	lileu nelow and on any attached continuation	y other than the United States	of America listed b	elow and on any
Prior foreign/PCT application(s):				
200104685-4	Singapore	<u>06/08/01</u>	Priority Claimed	
(number)	(country)	(day/month/year filed)	Yes	No
(number) I hereby claim the benefit under Title 35. I	(country)	(day/month/year filed)	Yes	No
application is not disclosed in any such prior application is not disclosed in any such prior applications to the U.S. Patent and Tradem Regulations § 1.56 which became available bet	prication in the manner provided by the first ark Office all information known to me to be ween the filing date of such prior application	and, insofar as the subject managraph of Title 35, United	States Code, § 112	claims of this , I acknowledge the
	(filing date)	(status - pending, patented or abandoned)		
(application serial no.)	(filing date)	(status - pending, patented or abandoned)		
I hereby claim the benefit under Title 35, U	nited States Code, § 119(e) of any United Sta	tes provisional application(s)	listed below:	
(provisional application no.)	(filing date)			
I hereby appoint the following Registered Pr therewith: David V. Trask, Reg. No. 22,012 Joseph A. Walkowski, Reg. No. 28,765 Allen C. Turner, Reg. No. 33,041 Brick G. Power, Reg. No. 38,581 Krista Weber Powell, Reg. No. 47,867 Shawn G. Hansen, Reg. No. 42,627 Katherine A. Hamer, Reg. No. 47,628	William S. Britt, Reg. No. 20,969 James R. Duzan, Reg. No. 28,393 Edgar R. Cataxinos, Reg. No. 39,931 Paul C. Oestreich, Reg. No. 44,983 Jarett K. Abramson, Reg. No. 47,376 Bretton L. Crockett, Reg. No. 44,632 Michael L. Lynch, Reg. No. 30,871	Laurence B. Bond, Re H. Dickson Burton, R Kent S. Burningham, I Devin R. Jensen, Reg. David L. Stott, Reg. N Bradley B. Jensen, Re Charles B. Brantley II,	g. No. 30,549 eg. No. P-48,396 Reg. No. 30,453 No. 44,805 Io. 43,937 g. No. 46,801	c Office connected
TRASI P.O. 1	ey B. Jensen, telephone no. (801) 532-1922. KBRITT, PC BOX 2550 ake City, Utah 84110	,	3	
I hereby declare that all statements made her and further that these statements were made with both, under Section 1001 of Title 18 of the Unit issued thereon.				
Full name of first joint inventor: Setho Sing Fed Inventor's signature	•			
Residence: Singapore Citizenship: Republic of Singapore Post Office Address: Block 91, Bedok North St		Date		

Invention title: QUAD FLAT NO LEAD (QFN) GRID ARRAY PACKAGE, METHOD OF MAKING MEMORY MODULE AND COMPUTER SYSTEM INCLUDING SAME

Date

Inventor name(s) appearing on first declaration page: Setho Sing Fee

Additional original, first and joint inventor(s):

Full name of second joint inventor: Lim Thiam Chye

Inventor's signature

Residence: Singapore
Citizenship: Republic of Singapore
Post Office Address: Block 224, Simei Street 4 #11-98, Singapore 520224